ASMPT enabling the digital world

SIPLACE V

The new era in placement technology

SIPLACE V BOOSTS YOUR **INTELLIGENT FACTORY**

↑30% MORE REAL PERFORMANCE

UNLIMITED FLEXIBILITY

100% PROCESS EXCELLENCE

READY FOR THE FUTURE

Powerful. Precise. Future-proof.

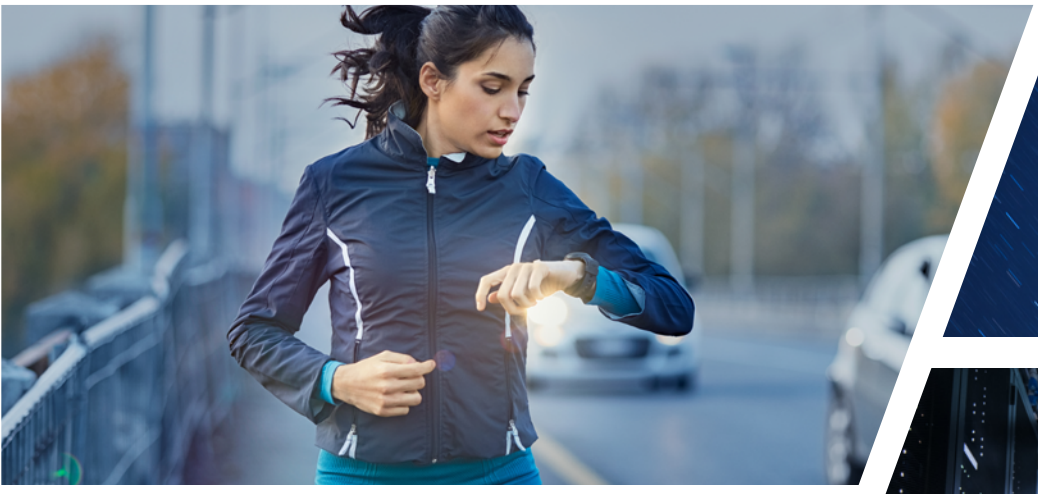
With performance increases of up to 30 percent under real-life factory conditions, the SIPLACE V platform represents more than the next generation of placement machines.

It marks the beginning of a new era in terms of space efficiency, quality, flexibility, and investment protection.

Fully compatible with existing machines, feeders and software solutions from ASMPT, it is perfectly equipped for big data processing, AI and automation – making it ready for the future in all aspects.

More about the SIPLACE V

FIT FOR THE KEY
INDUSTRIES OF THE FUTURE



Electronics manufacturing facilities are as diverse as the products they deliver, but they have one thing in common: their need for top quality, flexibility, and cost-effectiveness.

This is precisely what the SIPLACE V was developed for. It adapts seamlessly to a wide variety of production environments and impresses its users with precision, stability and efficiency – regardless of product quantities, types, and complexities. It demonstrates its particular strengths most of all in the key industries of the future, in which performance, process stability and investment protection are crucial for success.

Automotive & Industry: In the automotive and industry sector, control and power electronics must satisfy the highest requirements in terms of quality, process stability, and traceability. Rework is not an option, and zero-fault strategies are standard. The SIPLACE V offers the flexibility and process stability that this industry demands.

Consumer electronics: High production volumes, short cycle times and maximum line utilization characterize the consumer segment. This is where the SIPLACE V impresses with the highest placement rates, stable real performance and speedy product changeovers for maximum overall equipment effectiveness at low operating costs.

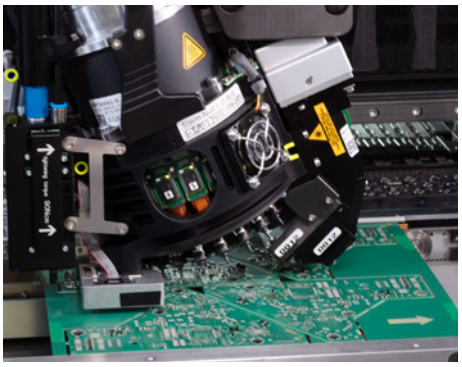
Smartphones: Speed, precision and process stability are what matters most in the smartphone segment. The SIPLACE assembles highly integrated, densely packed circuit boards with complex layouts and exotic components ranging from 016008M to large OSCs with maximum precision.

IT & network infrastructure: Oversized PCBs, complex designs and hybrid signal transfers between electronics and optics place high demands on the placement technology. The SIPLACE V offers the necessary flexibility and precision for these requirements.

↑30 % MORE REAL PERFORMANCE
NOTICEABLE AND MEASURABLE

New standards in speed and space productivity

- **A completely redesigned platform:** Reinforced frames and fasteners ensure maximum stability.
- **Highly efficient linear drives:** For faster acceleration along the main axes and optimized travel paths for maximum placement performance.
- **Improved placement heads:** A new generation of placement heads with high-resolution camera systems delivers higher speeds and more precision.
- **Outstanding space productivity:** More performance per square meter thanks to compact design and optimized space utilization in a footprint of only 1.1 × 2.4 meters.
- **Proven performance:** The SIPLACE V delivers up to **30 % more performance under real production conditions in the key markets of today and tomorrow.**



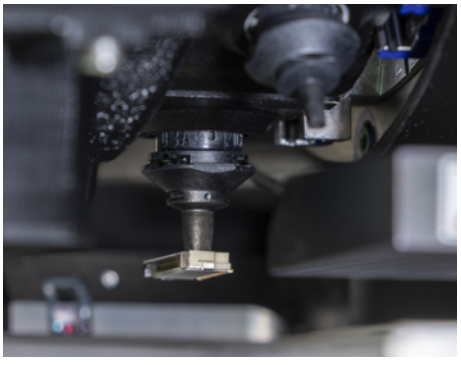
Peak performance of up to 52,500 cph in a compact footprint of only 1.1 × 2.4 meters.

100 % PROCESS EXCELLENCE
QUALITY WITHOUT COMPROMISES

Maximum precision and constant process stability in every detail

- **Maximum precision:** New linear drives and high-resolution measurement systems enable placements with an accuracy of up to 25 µm @ 3σ.
- **Intelligent sensor technology:** Closed-loop controls adapt the placement force in real time and ensure a consistently high level of quality for every component.
- **Perfect alignment:** ASMPT's unique rotatable nozzle segments ensure precise angular alignments for error-free placements.
- **Automated quality assurance:** High-resolution cameras inspect each component, and variable pickup positions and board warps are automatically compensated.
- **Seamless traceability:** Complete traceability of all components – ideal for automotive and high-reliability applications.
- **Process reliability for complex components:** Automatic Smart Pin Support and improves OSC processing guarantee stable results even with special components.

Smart Pin Support prevents PCB bending at critical points.



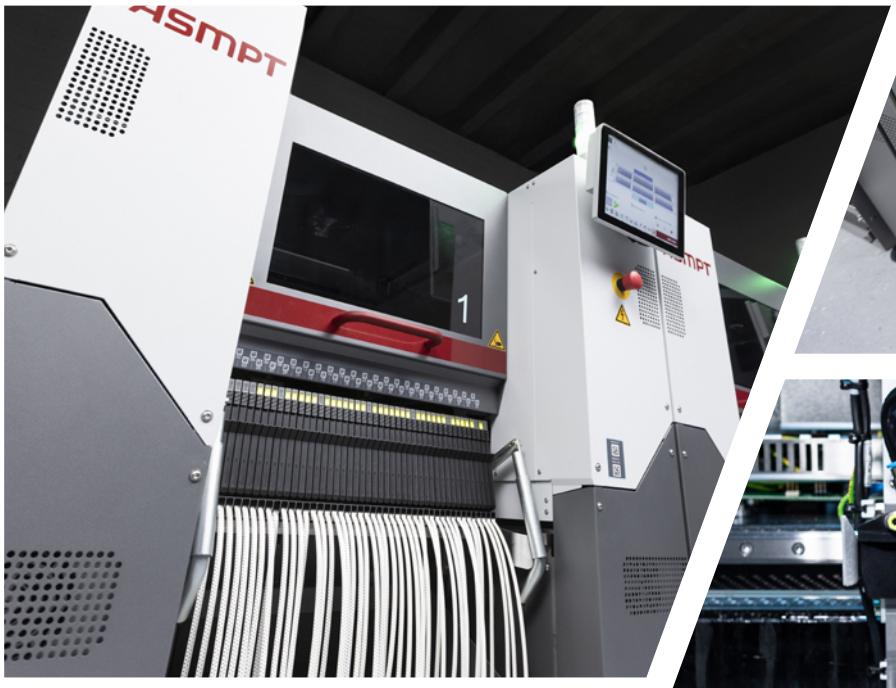
Rotatable nozzle segment precisely align with the components already during the pickup process.

UNLIMITED FLEXIBILITY
FOR ANY PRODUCTION

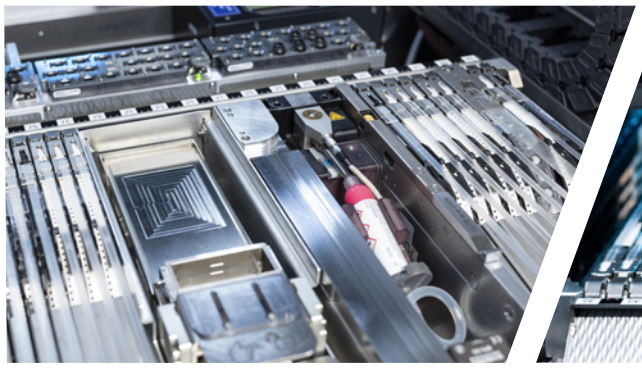
High-speed, mixed assembly or odd-shaped components – the right solution for every requirement

- **Comprehensive component spectrum:** The SIPLACE V masters the complete spectrum – from ultra-small 016008M chips to large odd-shaped components and BGAs.
- **Three improved placement heads:** The optimal choice for any production requirement. Thanks to their universal head interface, changing them is quick and easy, even during operation.
- **Expanded feeder capacity:** Up to 45 8-mm feeder on each side are usable irrespective of the options selected. Compatible with all SIPLACE X feeders as well as the Linear Dipping Unit, Power Connector, Glue Feeder, and Measuring Feeder.
- **Flexible transport system:** Single or dual conveyor for varying board sizes and production requirements.
- **Variable machine configuration:** Single- or double-gantry versions, single- or dual-track conveyors, optional 3D Coplanarity Module and additional cameras offer maximum adaptability for any production line.

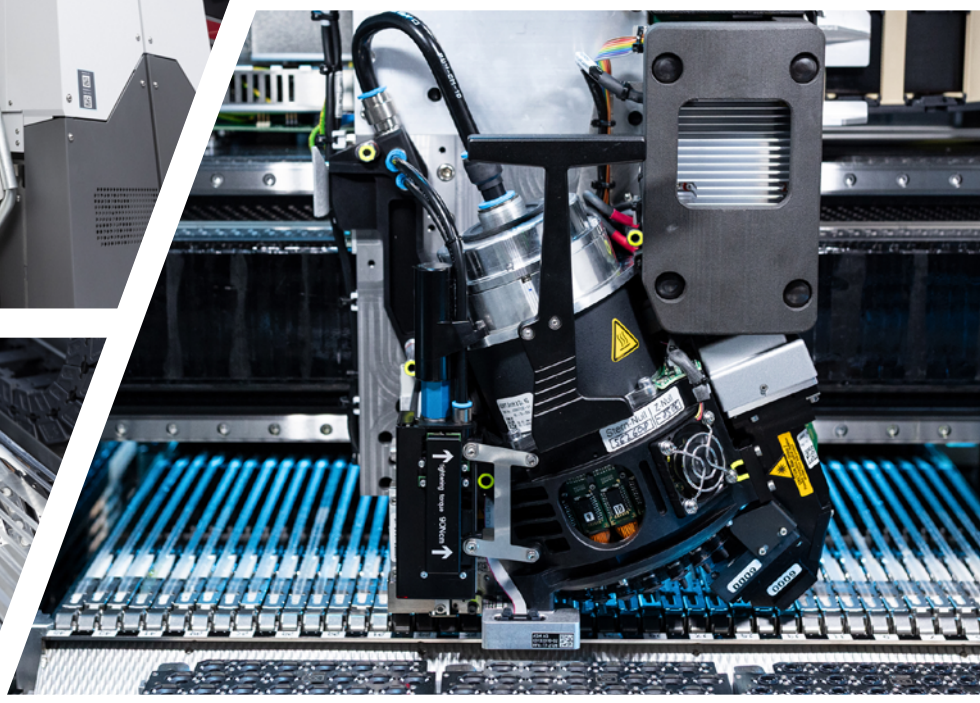
45 open 8-mm slots at each location, irrespective of installed options.



New slim and space-saving Tray Unit V.



Fully compatible with all SIPLACE X feeders, Linear Dipping Unit, Power Connector, Glue Feeder, and Measuring Feeder.



Placement Head CP20: High-speed collect-and-place placement head with up to 52,500 cph at 25 µm @ 3σ placement accuracy.

TODAY AND TOMORROW
READY FOR THE FUTURE

The SIPLACE V combines today's top performance with future viability

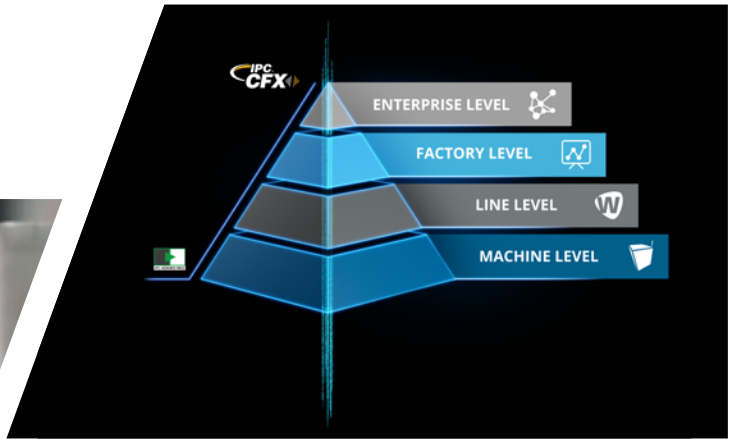
- **Open system architecture:** With its modular design from the ground up, the SIPLACE V is ready for new placement head generations and future process requirements.
- **High-speed data communication:** Gigabit Ethernet for maximum bandwidth, minimal latency, seamless M2M communication and efficient big data management including analysis functions.
- **Ready for AI and data analytics:** An integrative data concept forms the basis for AI-supported process optimization and predictive quality control.
- **Automation-ready:** Designed today for tomorrow's autonomous feeder technology and further automation steps in electronics production.
- **Future-proof investment:** Like all ASMPT solutions, the SIPLACE V is fully compatible with existing machines, feeders, and the entire ASMPT software portfolio.

Software integration – the basis for intelligent manufacturing processes

ASMPT offers powerful software solutions for all levels of electronics production – from the machine level to the line, shop floor and enterprise level. They connect processes, improve transparency and efficiency, and actively support manufacturers on their journey to the fully digitized, intelligent factory of the future.

- **WORKS Software Suite:** WORKS applications bring production lines into top form, relieve employees, and control production and material flows efficiently and transparently. Open interfaces make it easy to link MES and ERP solutions.
- **Factory Solutions:** With its Factory Solutions, ASMPT supports intelligent intralogistics, asset and maintenance management and process analytics along the SMT line. AI-supported assistance systems help users make decisions in real time, raise the availability of production systems, and continuously improve quality and productivity.

Open standards like IPC-HERMES-9852 and IPC-CFX ensure consistent M2M and M2H communication throughout the enterprise.

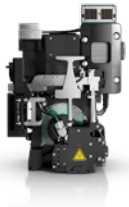
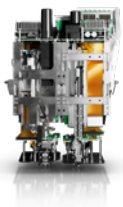


Latency-free data transmission with free-space optics provides the foundation for big data applications.

WORKS Software Suite – the platform for the intelligent factory: Efficient workflows, autonomous process optimization, and seamless systems integration.

SIPLACE V
TECHNICAL SPECIFICATIONS

Specifications	SIPLACE V
Placement speed (benchmark rating)	105,000 cph
Machine dimensions (L x W)	1.1 m × 2.4 m
Feeder capacity	90 8-mm slots
Placement heads	Placement Head CP20, Placement Head CPP, Placement Head TWIN, Placement Head TWIN VHF
Transport	Single conveyor, flexible dual conveyor
Component spectrum	016008M to 200 mm × 150 mm × 28 mm
PCB dimensions (L x W)	850 mm × 610 mm with single conveyor 700 mm × 520 mm with dual conveyor (in single-conveyor mode) 400 mm × 280 mm with dual conveyor (in dual-conveyor mode)
Component supply	Tapes, trays

Placement head	Placement Head CP20	Placement Head CPP	Placement Head TWIN
			
Component spectrum	016008M to 8.2 × 8.2 mm	01005 to 50 mm × 40 mm	0201 to 200 mm × 150 mm
Maximum component height	2 mm or 4 mm	15.5 mm	28 mm
Placement accuracy	25 µm at 3 σ	25 µm at 3 σ	20 µm at 3 σ
Maximum placement speed	52,500 cph	28,000 cph	6,000 cph
Placement force	4.5 N	15 N	100 N

ASMPT

ASMPT GmbH & Co. KG
Rupert-Mayer-Strasse 48 | 81379 Munich | Germany | Phone: +49 89 20800-22000 | Email: smt-solutions.de@asmpt.com

ASMPT SMT Solutions Website

smt.asmpt.com

ASMPT Website

asmpt.com

ASMPT SMT Solutions LinkedIn

www.linkedin.com/company/asmpt-smt-solutions/

ASMPT SMT Solutions Facebook

www.facebook.com/ASMPTSMTSolutions

ASMPT SMT Solutions YouTube

www.youtube.com/c/ASMPTSMTSolutions

Edition 2/02-2026 | All rights reserved. | Order No.: A22-ASMPT-A378-EN | Printed in Germany | © ASMPT GmbH & Co. KG